

MSKSEMI 美森科

SEMICONDUCTOR



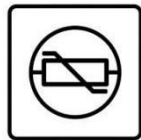
ESD



TVS



TSS



MOV



GDT



PLED

SK32 THRU SK310

Product specification


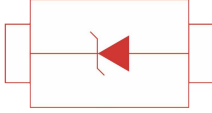
FEATURES

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Terminals: Solder plated, solderable per MIL-STD-202F , method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.063 gram

Reference News

SMA(DO-214AC)	Schematic Diagram
	

Marking

SK32	SK33	SK34	SK35	SK36	SK38	SK39	SK310
SK32	SK33	SK34	SK35	SK36	SK38	SK39	SK310

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SK32	SK33	SK34	SK35	SK36	SK38	SK39	SK310	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current	3.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80								A
Maximum Instantaneous Forward Voltage at 3.0A	0.55		0.70		0.85				V
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C		0.1		0.02				mA
	Ta=100°C		5		2				mA
Typical Junction Capacitance (Note1)	300								pF
Typical Thermal Resistance R _{JL} (Note 2)	10								°C/W
Operating Temperature Range T _J	-65 — +150								°C
Storage Temperature Range T _{STG}	-65 — +150								°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

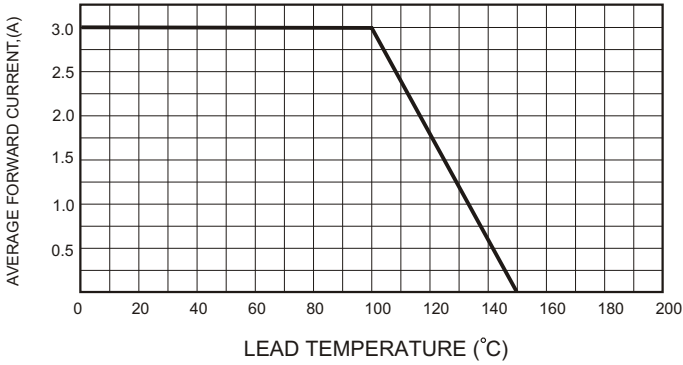


FIG.2-TYPICAL FORWARD CHARACTERISTICS

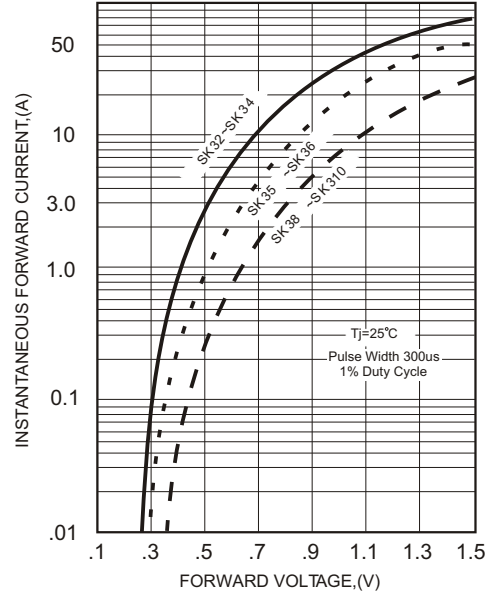


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

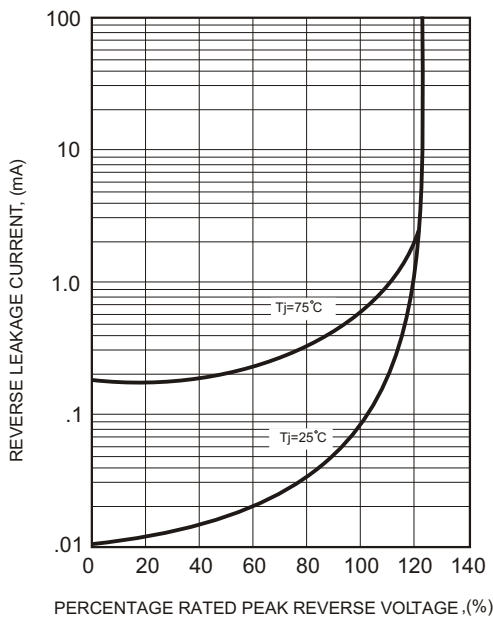


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

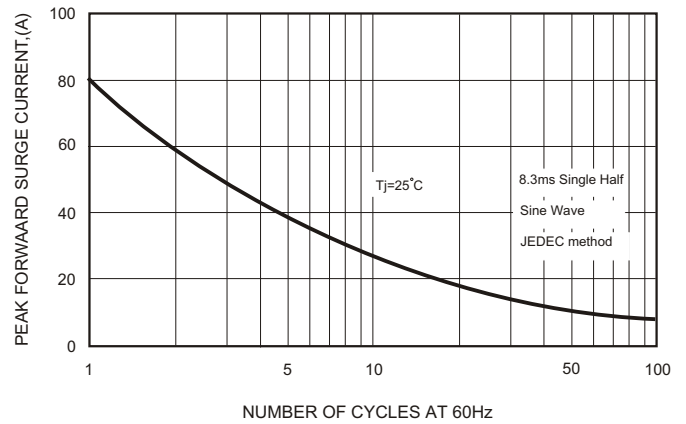
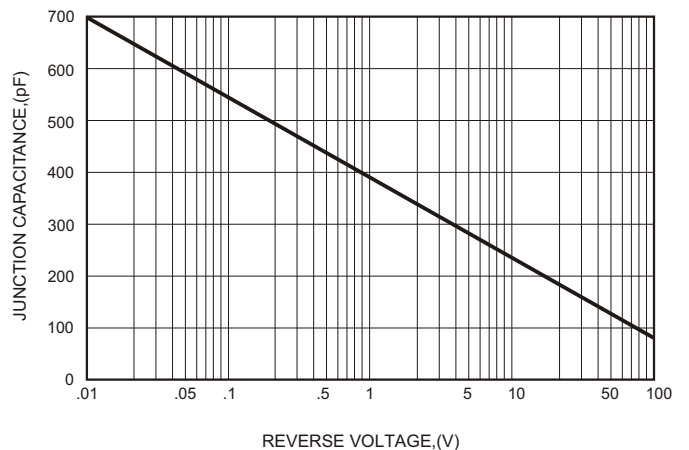
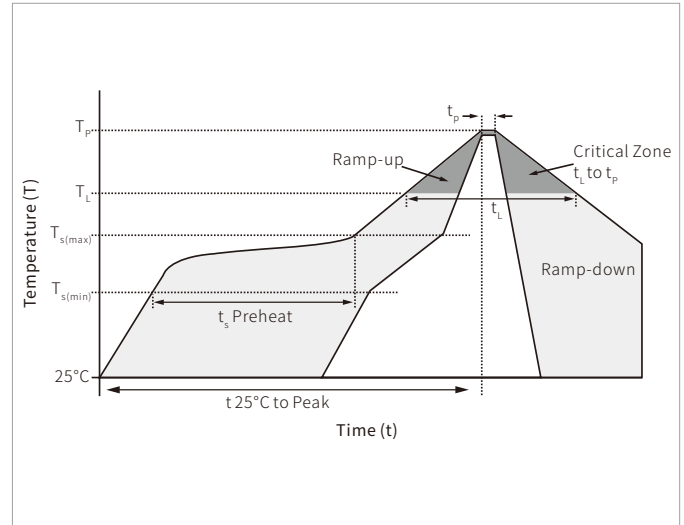


FIG.5-TYPICAL JUNCTION CAPACITANCE

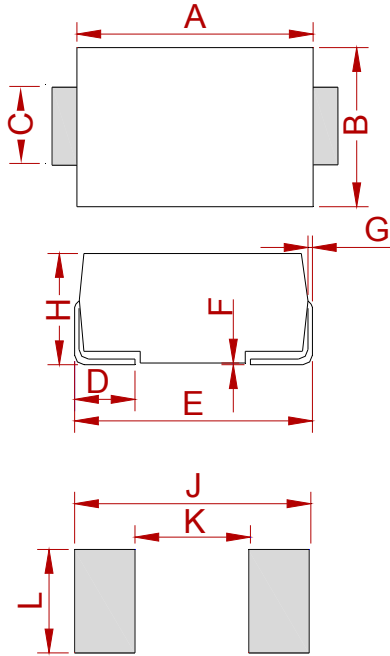


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



PACKAGE MECHANICAL DATA



DO-214AC (SMA)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SK32 THRU SK310	DO-214AC (SMA)	2000PCS

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